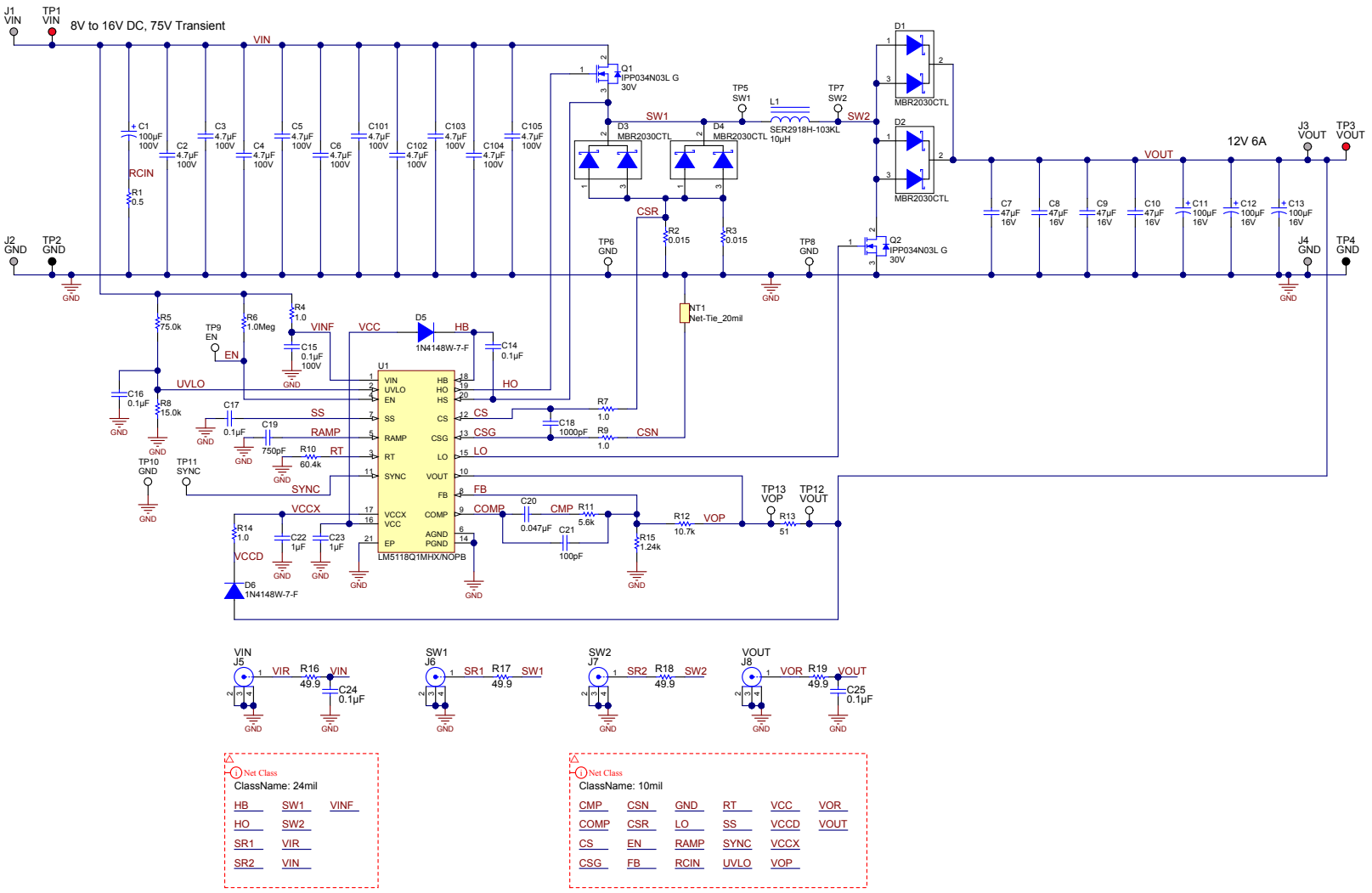

Designed for: Public Release	Mod. Date: 6/26/2013
Project Title: LM5118Q Two Switch Buck Boost	
Sheet Title: LM5118Q Two Switch Buck Boost	
Number: PMP7905 Rev: A1	Assembly Variant: 001
SVN Rev: Not in version control	Sheet: 1 of 2
Drawn By:	File: PMP7988_REV1.SchDoc Size: B
Engineer: Robert Sheehan	Contact: http://www.ti.com/support

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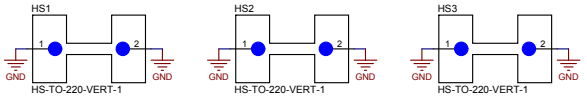
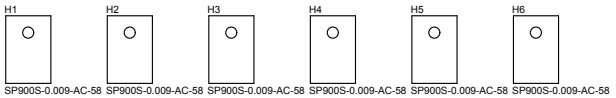
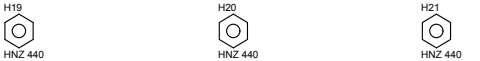
PCB Number: PMP7905
PCB Rev: A

FID1 FID2 FID3
FID4 FID5 FID6

PCB
LOGO
Texas Instruments







Revision History	
Revision	Notes
A	Initial design 1/30/2013
A1	Add C101-C105 2/12/2013

LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

Designed for: Public Release		Mod. Date: 6/26/2013	
Project Title: LM5118Q Two Switch Buck Boost			
Number: PMP7905	Rev: A1	Sheet Title: LM5118Q Two Switch Buck Boost Hardware	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet 2 of 2
Drawn By:		File: PMP7988_REV1_Hardware.SchDoc	Size: B
Engineer: Robert Sheehan		Contact: http://www.ti.com/support	

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